

ZPMV2.E80943 - Wiring, Printed - Component

Wiring, Printed - Component

Alpha Circuit I LLC.
 730 N Oaklawn Ln
 Elmhurst, IL 60126 United States


E80943

Type	Cond Width			Max Report				Assembly			Max			Meets C	I
	Min	Cond	SS/	Area	Date	Surface	Solder	Solder	Oper	Temp	Flame	UL796			
	Min	Edge	Thk	DS/	Diam	After	Mount	Process	Process	Limits	Temp	Class	DSR	T	
	mm	mm	mic	DSO	mm	2022-01-01	Technology	°C	Cycles	°C	sec	°C	Class	DSR	I
Multilayer mass laminated printed wiring boards															
2-0	0.13	0.38	34.3	DS	50.8	No	-	-	-	271	10	105	V-0	All	-
2-0G	0.10	0.10	17.8	DS	25.4	No	-	-	-	274	15	130	V-0	All	-
Multilayer printed wiring boards															
3-0	0.1	0.1	17.8 Int:70	DS	25.4	No	-	-	-	274	15	130	V-0	All	-
3-0G	0.10	0.10	17.8 Int:70	DS	25.4	No	-	-	-	-	-	130	V-0	All	-
								-	-	274	15				
4-0	0.1	0.1	17 Int:102	DS	25.4	No	-	-	-	274	15	130	V-0	▲	-
4A-0	0.1	0.1	17 Int:68	DS	38.1	No	-	-	-	274	15	130	V-0	All	-
6 0	0.05	0.05	8.5 Int:102	DS	127	No	-	-	-	288	20	130	V-0	All	*
6-01	0.14	0.13	8.5 Int:102	DS	127	No	-	-	-	288	20	130	V-0	All	3
6-1	0.48	1.44	204 Int:204	DS	127	No	-	-	-	288	20	130	V-0	All	3
6-2 (ASP)	0.24	0.72	17 Int:136	DS	127.0	Yes	Yes	260	6	-	-	130	V-0	All	3

1)																
Single layer Metal Base printed wiring boards																
4-0	0.05	0.05	33	SS	101.6	No	-	-	-	274	15	125	V-0	All	-	
4-0G	0.05	0.05	33	SS	101.6	No	-	-	-	-	-	125	V-0	All	-	
									-	-	274	15				
5-0	0.10	0.10	33	SS	101.6	No	-	-	-	274	15	125	V-0	-	-	
5-0G	0.10	0.10	33	SS	101.6	No	-	-	-	-	-	125	V-0	All	-	
									-	-	274	15				
6-0	0.07	0.12	68	SS	101.6	No	-	-	-	274	15	90	V-0	All	-	
6-0G	0.07	0.12	68	SS	101.6	No	-	-	-	-	-	90	V-0	All	-	
									-	-	274	15				
7-0G (ASP 1)	0.10	0.30	34	SS	101.6	Yes	Yes	260	6	-	-	125	V-0	All	0	
8-0G (ASP1)	0.21	0.63	34	SS	101.6	Yes	Yes	260	6	-	-	125	V-0	-	0	
Single layer printed wiring boards																
1-0	0.10	0.10	17	DS	50.8	No	-	-	-	271	10	130	V-0	All	-	
1-0G	0.10	0.10	17.8	DS	25.4	No	-	-	-	274	15	130	V-0	All	-	
									-	-	-	-				
1A-0	0.10	0.10	17	DS	38.1	No	-	-	-	274	10	130	V-0	All	-	
3-0	0.10	0.20	17	DS	12.7	No	-	-	-	138	7200	140	V-1	All	-	
									-	-	288	30				
5 0	0.05	0.05	8.5	DS	127	No	-	-	-	288	20	130	V-0	All	*	
5-2 (ASP 1)	0.24	0.72	17	DS	127.0	Yes	Yes	260	6	-	-	130	V-0	All	3	

* - CTI marking is optional and may be marked on the printed wiring board.

ASP 1 - Assembly solder process evaluated to IPC-TM-650, 2.6.27 Thermal Stress Simulation

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